

# SOT263B-01

plastic single-ended package; heatsink mounted; 1 mounting hole; 5-lead TO-220 lead form option

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Z (zig-zag)
<b>Package type descriptive code</b>	TO-220-5 option
<b>Package type industry code</b>	TO-220-5 option
<b>Package style descriptive code</b>	ZFM (zig-zag flange mount)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	5-lead (option) TO-220
<b>Mounting method type</b>	H (heatsink mount)
<b>Issue date</b>	11-1-2001

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.2	-	15.5	15.8	mm
E	package width	9.7	-	10	10.3	mm
A	seated height	4.1	-	4.3	4.5	mm
n <sub>2</sub>	actual quantity of termination	-	-	5	-	

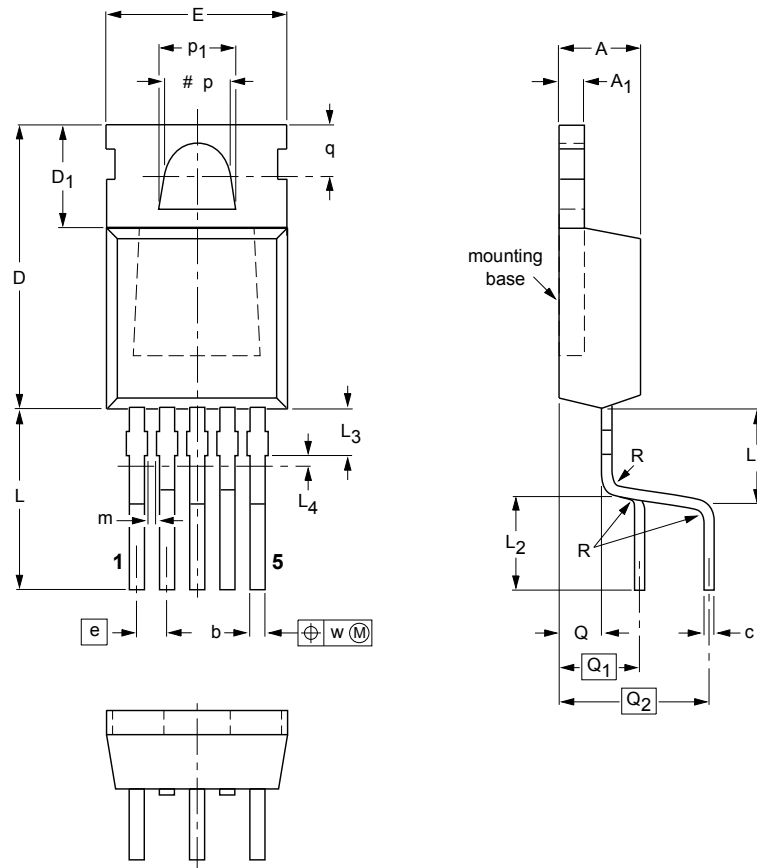


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## 2. Package outline

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	c	D	D <sub>1</sub>	E	e	L	L <sub>1</sub>	L <sub>2</sub>	L <sub>3</sub> <sup>(1)</sup>	L <sub>4</sub> <sup>(2)</sup> max.	m	# p	p <sub>1</sub>	q	Q	Q <sub>1</sub>	Q <sub>2</sub>	R	w
mm	4.5 4.1	1.39 1.27	0.85 0.70	0.7 0.4	15.8 15.2	6.4 5.9	10.3 9.7	1.7	9.8 9.7	5.9 5.3	5.2 5.0	2.4 1.6	0.5	0.8 0.6	3.8 3.6	4.3 4.1	3.0 2.7	2.0	4.5	8.2	0.5	0.4

**Notes**

- Terminal dimensions are uncontrolled in this zone.
- Positional accuracy of the terminals is controlled in this zone.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT263B-01		5-lead (option) TO-220			01-01-11

Fig. 1. Package outline TO-220-5 option (SOT263B-01)

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### 3. Legal information

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)  
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